

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	789616	(semiconductor chip die ic (integrated adj circuit)) same (substrate carrier pcb ((wiring printed circuit) adj3 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:55
L2	140738	bga bump ball and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:55
L3	73064	(bga bump ball) and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:55
L4	17019	3 and (((non without) adj thermosetting) thermoplastic polymer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:57
L5	122980	(peripheral boundary edge end corner) with (((non without) adj thermosetting) thermoplastic polymer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:58
L6	1340	4 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:58
L7	4212841	(heating heat heated remove removing removed) and "7"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:59
L8	1273	(heating heat heated remove removing removed) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 11:59

L9	4535956	(heating heat heated temperture) (remove removing removed) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 12:00
L10	951	(heating heat heated temperture) and (remove removing removed) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 12:00